

<b>PATENT ASSIGNMENT COVER SHEET</b>
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Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT5354805

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
MINGZHU WANG	11/12/2018
ZHENYU CHEN	10/25/2018
NAN GUO	10/31/2018
TAKEHIKO TANAKA	11/02/2018
BOJIE ZHAO	10/23/2018
ZILONG DENG	10/31/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	NINGBO SUNNY OPOTECH CO., LTD.
<b>Street Address:</b>	66-68, SHUNYU ROAD, YUYAO,
<b>City:</b>	NINGBO, ZHEJIANG
<b>State/Country:</b>	CHINA
<b>Postal Code:</b>	315400
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16157061
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(626)571-9813
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	626-571-9812
<b>Email:</b>	raymondc@davidandraymond.com, mayz@davidandraymond.com
<b>Correspondent Name:</b>	DAVID AND RAYMOND PATENT FIRM
<b>Address Line 1:</b>	108 N. YNEZ AVE., SUITE 128
<b>Address Line 4:</b>	MONTEREY PARK, CALIFORNIA 91754
<b>ATTORNEY DOCKET NUMBER:</b>	USCP10486C/NB4318-SYO
<b>NAME OF SUBMITTER:</b>	MICHAEL LEE
<b>SIGNATURE:</b>	/Michael Lee/
<b>DATE SIGNED:</b>	02/01/2019
<b>Total Attachments: 6</b>	

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## ASSIGNMENT

WHEREAS, I (we), Mingzhu Wang  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Camera Module, Molded Circuit Board Assembly, Molded Photosensitive Assembly and Manufacturing  
Method Thereof  
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even data herewith

executed on:

filed on: 10/10/2018

Serial No.: 16/157,061

WHEREAS, Ningbo Sunny Optotech Co., Ltd.  
whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400  
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the  
same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby  
acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the  
entire right, title, and interest in and to said INVENTION and application throughout the United States of  
America, including any and all Letters Patent granted on any division, continuation, continuation-in-part  
and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in  
connection with the filing, prosecution and maintenance of said application or any other patent  
application(s) in the United States for said INVENTION, including additional documents that may be  
required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration.  
ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and  
communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the  
INVENTION that are within ASSIGNOR'S possession or control, and to provide further assurances and  
testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the  
prosecution, maintenance and defense of any patent application or patent encompassed within the terms of  
this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs,  
executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks  
to issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title  
and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of  
ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent  
may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment  
and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Mingzhu Wang

ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Mingzhu Wang  
SIGNATURE

2018.11.12.  
DATE

## ASSIGNMENT

WHEREAS, I (we), Zhenyu Chen  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Camera Module, Molded Circuit Board Assembly, Molded Photosensitive Assembly and Manufacturing  
Method Thereof

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even data herewith

executed on:

filed on: 10/10/2018

Serial No.: 16/157,061

WHEREAS, Ningbo Sunny Optotech Co., Ltd.  
whose post office address is 66-68 Shenyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400  
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the  
same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby  
acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the  
entire right, title, and interest in and to said INVENTION and application throughout the United States of  
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and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Zhenyu Chen  
ADDRESS: 66-68 Shenyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Zhenyu Chen

SIGNATURE

2018.10.25

DATE

## ASSIGNMENT

WHEREAS, I (we), Nan Guo  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Camera Module, Molded Circuit Board Assembly, Molded Photosensitive Assembly and Manufacturing  
Method Thereof  
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even data herewith  
 executed on:  
 filed on: 10/10/2018 Serial No.: 16/157,061

WHEREAS, Ningbo Sunny Optech Co., Ltd.  
whose post office address is 66-68 Shanyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400  
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the  
same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby  
acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the  
entire right, title, and interest in and to said INVENTION and application throughout the United States of  
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and sale not been made.

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needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Nan Guo  
ADDRESS: 66-68 Shanyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

\_\_\_\_\_  
SIGNATURE

\_\_\_\_\_  
DATE

**ASSIGNMENT**

WHEREAS, I (we), Takehiko Tanaka  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Camera Module, Molded Circuit Board Assembly, Molded Photosensitive Assembly and Manufacturing  
Method Thereof

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even data herewith

executed on:

filed on: 10/10/2018

Serial No.: 16/157,061

WHEREAS, Ningbo Sunny Opotech Co., Ltd.  
whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400  
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the  
same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby  
acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the  
entire right, title, and interest in and to said INVENTION and application throughout the United States of  
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may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment  
and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Takehiko Tanaka

ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Takehiko Tanaka  
SIGNATURE

2018.11.2  
DATE

## ASSIGNMENT

WHEREAS, I (we), Bojie Zhao  
 whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
 certain new and useful improvements in  
Camera Module, Molded Circuit Board Assembly, Molded Photosensitive Assembly and Manufacturing  
 Method Thereof  
 (hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on even date herewith

executed on:

filed on: 10/10/2018

Serial No.: 16/157,061

WHEREAS, Ningbo Sunny Optech Co., Ltd.  
 whose post office address is 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400  
 hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the  
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 and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
 needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Bojie Zhao

ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

SIGNATURE

DATE

**ASSIGNMENT**

WHEREAS, I (we), Zilong Deng  
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a  
certain new and useful improvements in  
Camera Modulz, Molded Circuit Board Assembly, Molded Photosensitive Assembly and Manufacturing  
Method Thereof  
(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

executed on given data herewith  
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 filed on: 10/10/2018 Serial No.: 16/157,061

WHEREAS, Ningbo Sunny Opotech Co., Ltd.  
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ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent  
may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment  
and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document  
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Zilong Deng  
ADDRESS: 66-68 Shunyu Road, Yuyao City, Ningbo, Zhejiang Province, China 315400

Zilong Deng  
SIGNATURE

2018.10.31  
DATE